

## AMENDMENTS TO THE CLAIMS

**1 to 17. (Canceled)**

**18. (Currently Amended)** A photosensitive material for photolithographic patterning which comprises, as an integral layered body:

(a) a substrate; and

(b) a photoresist layer having a thickness in the range of from 100 to 570 nm formed on the surface of the substrate from a chemical-amplification positive-working photoresist composition which comprises as a uniform solution in an organic solvent:

an organic-acid generating compound capable of generating an acid by the irradiation with actinic rays;

a resinous composition having acid-dissociable groups and capable of being imparted with increased solubility in an aqueous alkaline solution by interaction with an acid; and

a surface active agent in a concentration lower than 10 ppm by weight based on the amount of the resinous composition and

(c) said ~~substrate~~ surface active agent, prior to the formation of said photoresist layer, having ~~an adsorbent thereon for said surface active agent~~ been removed as completely as possible by using an adsorbent.